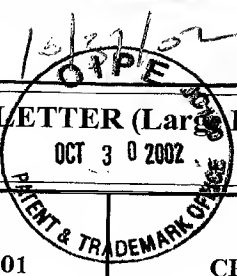


2827



AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): **Sudhakar BOBBA, et al.**

Docket No.

03226.147001; P6841

Serial No.

09/997,438

Filing Date

November 29, 2001

Examiner

CRUZ, Lourdes C.

Group Art Unit

2827

Invention:

150 DEGREE BUMP PLACEMENT LAYOUT FOR AN INTEGRATED CIRCUIT POWER GRID

TO THE ASSISTANT COMMISSIONER FOR PATENTS:



32615

PATENT TRADEMARK OFFICE

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	22 -	22 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	4 -	4 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

☒ No additional fee is required for amendment.

☐ Please charge Deposit Account No.

in the amount of

A duplicate copy of this sheet is enclosed.

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to cover the filing fee is enclosed.

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☐ Any additional filing fees required under 37 C.F.R. 1.16.

☒ Any patent application processing fees under 37 CFR 1.17.

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Facsimile: (713) 228-8778

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CERTIFICATE OF MAILING BY "EXPRESS MAIL" (37 CFR 1.10)

Applicant(s): **Sudhakar BOBBA et al.**

Docket No.

03226.147001; P6841

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November 29, 2001

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CRUZ, Lourdes C.

Group Art Unit

2827

Invention: **150 DEGREE BUMP PLACEMENT LAYOUT FOR AN INTEGRATED CIRCUIT POWER GRID**

I hereby certify that the following correspondence:

Response to Office Action

(Identify type of correspondence)

is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 in an envelope addressed to: The Assistant Commissioner for Patents, Washington, D.C. 20231 on

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Sudhakar BOBBA et al. ✓
Serial No.: 09/997,438
Filed : November 29, 2001 ✓
Title : 150 DEGREE BUMP PLACEMENT LAYOUT FOR AN INTEGRATED
CIRCUIT POWER GRID

Art Unit : 2827
Examiner : Lourdes CRUZ

Assistant Commissioner for Patents
Washington, DC 20231



32615

PATENT TRADEMARK OFFICE

REPLY UNDER 37 CFR § 1.111

Dear Sir:

In response to the Office Action dated August 14, 2002, please amend the application as follows and consider the included remarks.

IN THE CLAIMS:

Please amend claims 1-22 as follows [a marked-up copy of the amended claims is provided in Appendix B]:

1 An integrated circuit having a top metal layer, the top metal layer having a first metal bar and a second metal bar, the integrated circuit comprising:

- a first bump disposed on the first metal bar;
a second bump disposed on the first metal bar; and
a reference bump disposed on the second metal bar,

wherein the first bump and the second bump are positioned such that an angle between a line from the reference bump to the first bump and a line from the reference bump to the second bump has a value substantially equal to 150 degrees.

2 The integrated circuit of claim 1, wherein the first bump, the second bump, and the reference bump form a bump structure that is repeated across the top metal layer to form a patterned bump array.

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